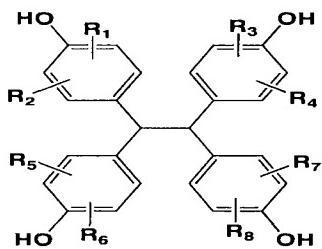


ABSTRACT

Disclosed is a photosensitive resin composition comprising a resin (A) soluble in an aqueous alkaline solution, a crosslinking agent (B), a photopolymerization initiator (C) and a curing agent (D) wherein the curing agent (D) is an epoxy compound obtained by glycidylating a compound containing not less than 80% of a tetraphenylethane derivative represented by the following formula (1).



(1)

In the formula, R₁ to R₈ independently represents a hydrogen atom, a C₁-C₄ alkyl group or a halogen atom.